Data Brief



SiI9287B HDMI Port Processor with InstaPort Viewing Technology

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Further Information

The SiI9287B port processors include an implementation of Silicon Image Mobile High-Definition Link (MHLTM) technology—hereinafter referred to simply as MHL technology. This implementation conforms to the 0.71 draft specification and will not be compatible with future revisions of the specification.

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Introduction

The SiI9287B HDMI Port Processor with InstaPort Viewing Technology is the second generation of HDMI devices that support the HDMI Specification. With four HDMI/Mobile HD Link (MHL) inputs and a single output, the SiI9287B port processor enhances the functionality of digital TVs using single system on a chip (SoC) solutions with integrated HDMI receivers. The port processor provides a simple, low-cost method of retransmitting digital audio and video to give consumers a truly all-digital experience. Built-in backward compatibility with DVI 1.0 allows HDMI systems to connect to any DVI 1.0 source.

Features

The SiI9287B device brings cutting edge innovations, such as:

- InstaPortTM viewing technology that reduces port switching time to less than one second
- Enhanced cable equalization for long cable support, even at Deep Color resolutions that enables the SiI9287B device to work with noisy signals and many sources, making the sink devices highly interoperable
- MHL for connection to mobile devices
- Integrated EDID and CEC functions
- Improved ESD protection on all signals connected to the HDMI connector.

HDMI Inputs and Output

Four HDMI input ports and single output port support:

- HDMI, HDCP, and DVI compatibility
- TMDS[®] cores run at 25–225 MHz
- Supports video resolutions up to 1080p, 60 Hz, 12bit or 720p/1080i, 120 Hz, 12-bit

Control Capability

- Consumer Electronics Control (CEC) interface incorporates an HDMI-compliant CEC I/O and an integrated CEC Programming Interface (CPI); these simplify design and lower costs and software overhead
- Integrated EDID and DDC support for 4 HDMI/DVI ports and 1 VGA port with a 256-byte NVRAM shared between ports that loads into SRAM separate 256-byte SRAM for each of 5 ports
- Individual control of Hot Plug Detect (HPD) for each of the 4 HDMI/DVI ports
- 5-volt detect to help speed soft mute of audio while plugging and unplugging
- Controllable by the local I²C bus

Power Management

- Flexible power management provides extremely low standby power consumption
- Standby power can be supplied from an HDMI 5-V signal or from a separate standby power pin
- Single power 3.3-V source
- Integrated 5 V to 3.3 V Voltage regulator

Package

• 72-pin, 10 mm x 10 mm, 0.5 mm pitch QFN package with enhanced ePadTM.

DTV (LCD, Plasma, Projector)

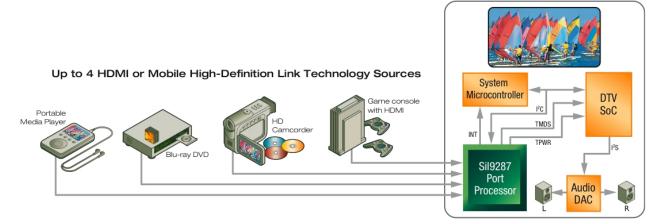


Figure 1. Typical Application of SiI9287B HDMI Port Processor

Pin Diagram

Figure 2 shows the pin diagram for the SiI9287B port processor. Pin names are generalized by type for this document. The list below the diagram describes the purpose of each type.

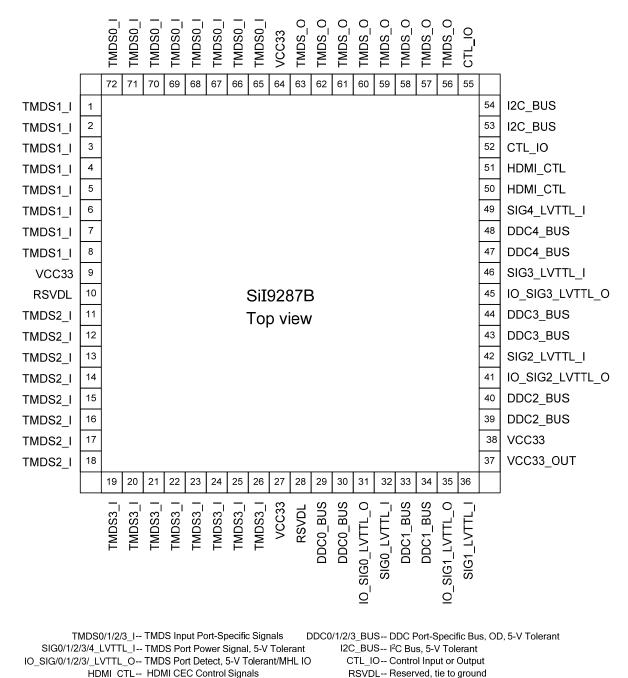


Figure 2. Pin Diagram (Top View)

TMDS O-- TMDS Output Port-Specific Signals

Package Information

ePad Requirements

The SiI9287B HDMI Port Processor with InstaPort Viewing Technology is packaged in a 72-pin 10 mm x 10 mm QFN package with an ExposedPadTM (ePad), used both for electrical connectivity and for improved thermal transfer characteristics. The ePad dimensions are 4.7 mm x 4.7 mm with a tolerance of ± 0.15 mm. Soldering of the ePad is **required** to meet package power dissipation requirements at full speed operation, and to correctly connect the chip circuitry to electrical ground.

Note: The ePad **must** be soldered to an electrically grounded plane on the PCB; it must not be electrically connected to any other voltage level except ground. A clearance of at least 0.25 mm should be designed on the PCB between the edge of the ePad and the inner edges of the lead pads to avoid electrical shorts.

The thermal land area on the PCB can use thermal vias to improve heat removal from the package. These thermal vias can double as ground connections, attaching internally in the PCB to the ground plane. An array of vias can be designed into the PCB beneath the package. For optimum thermal performance, Silicon Image recommends that the via diameter be 12 to 13 mils (0.30 to 0.33 mm) and the via barrel be plated with 1-ounce copper to plug the via. This plating helps avoid solder wicking inside the via during the soldering process, which can result in voids in solder between the exposed pad and the thermal land. If the copper plating does not plug the vias, the thermal vias can be tented with solder mask on the top surface of the PCB to avoid solder wicking inside the via during assembly. The solder mask diameter should be at least 4 mils (0.1 mm) larger than the via diameter.

Package stand-off is also a consideration. For a nominal stand-off of approximately 0.1 mm the stencil thickness of 5 to 8 mils should provide a good solder joint between the ePad and the thermal land.

Figure 3 on the next page shows the package dimensions of the SiI9287B package.

Package Dimensions

These drawings are not to scale.

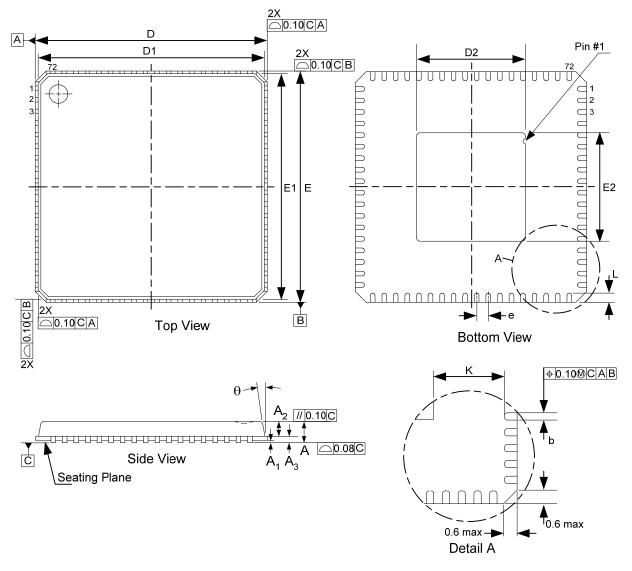


Figure 3. Package Diagram JEDEC Package Code MO-220

Item	Description	Min	Тур	Max
Α	Thickness		0.85	0.90
A1	Stand-off	0.00	0.01	0.05
A2	Body thickness	_	0.65	0.70
A3	Base thickness	0.20 REF		
D	Footprint	10.00 BSC		
Е	Footprint	10.00 BSC		
D1	Body size	9.75 BSC		
E1	Body size	9.75 BSC		

Item	Description	Min	Тур	Max
D2	ePad size	4.55	4.70	4.85
E2	ePad size	4.55	4.70	4.85
b	Plated lead width	0.18	0.23	0.30
e	Lead pitch		0.50 BSC	
K	ePad-to-pin clearance	0.20	_	
L	Lead foot length	0.30	0.40	0.50
θ	Lead foot angle		_	12°

Marking Specification

This drawing is not to scale.

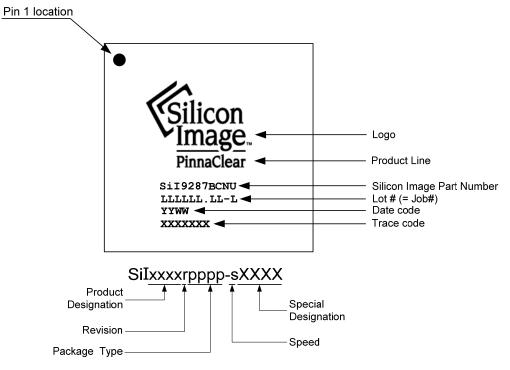


Figure 4. Marking Diagram

Ordering Information

Production Part Numbers:

Device	Part Number
Standard	SiI9287BCNU

The universal package may be used in lead-free and ordinary process lines.

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